

PTFE/Woven Fiberglass Laminates

Features:

- Extremely Low Loss Tangent
- Excellent Dimensional Stability
- Product Performance Uniformity

Benefits:

- Electrical Properties Are Highly Uniform Across Frequency
- Consistent Mechanical Performance
- Excellent Chemical Resistance

Typical Applications:

- Military Radar Feed Networks
- Commercial Phased Array Networks
- Low Loss Base Station Antennas
- Missile Guidance Systems
- Digital Radio Antennas
- Filters, Couplers, LNAs



DiClad laminates are woven fiberglass/PTFE composite materials for use as printed circuit board substrates. Using precise control of the fiberglass/PTFE ratio, DiClad laminates offer a range of choices from the lowest dielectric constant and dissipation factor to a more highly reinforced laminate with better dimensional stability.

The woven fiberglass reinforcement in DiClad products provides greater dimensional stability than nonwoven fiberglass reinforced PTFE based laminates of similar dielectric constants. The consistency and control of the PTFE coated fiberglass cloth allows Rogers to offer a greater variety of dielectric constants and produces a laminate with better dielectric constant uniformity than comparable nonwoven fiberglass reinforced laminates. The coated fiberglass plies in DiClad materials are aligned in the same direction. Cross-plied versions of many of these materials are available as CuClad materials.

DiClad laminates are frequently used in filter, coupler and low noise amplifier applications, where dielectric constant uniformity is critical. They are also used in power dividers and combiners, where low loss is important.

DiClad 527 (Er=2.40-2.65) use a

higher fiberglass/PTFE ratio to provide mechanical properties approaching conventional substrates. Other advantages include better dimensional stability and lower thermal expansion in all directions. The electrical properties of DiClad 527 are tested at 1MHz and 10GHz, respectively.

| Typical Properties: DiClad | | | | | |
|--|---|--------------------------------|-------------------------------|-------------------------------|-------------------------------|
| Property | Test Method | Condition | DiClad 880 | DiClad 870 | DiClad 527 |
| Dielectric Constant @ 10 GHz | IPC TM-650 2.5.5.5 | C23/50 | 2.17, 2.20 | 2.33 | 2.40 to 2.65 |
| Dielectric Constant @ 1 MHz | IPC TM-650 2.5.5.3 | C23/50 | 2.17, 2.20 | 2.33 | 2.40 to 2.65 |
| Dissipation Factor @ 10 GHz | IPC TM-650 2.5.5.5 | C23/50 | 0.0009 | 0.0013 | 0.0018 ¹ |
| Dissipation Factor @ 1 MHz | IPC TM-650 2.5.5.3 | C23/50 | 0.0008 | 0.0009 | 0.0010 |
| Thermal Coefficient of Er (ppm/°C) | IPC TM-650 2.5.5.5 Adapted | -10°C to +140°C | -160 | -161 | -153 |
| Peel Strength (lbs.per inch) | IPC TM-650 2.4.8 | After Thermal Stress | 14 | 14 | 14 |
| Volume Resistivity (MΩ-cm) | IPC TM-650 2.5.17.1 | C96/35/90 | 1.4 x 10 ⁹ | 1.5 x 10 ⁹ | 1.2 x 10 ⁹ |
| Surface Resistivity (MΩ) | IPC TM-650 2.5.17.1 | C96/35/90 | 2.9 x 10 ⁶ | 3.4 x 10 ⁷ | 4.5 x 10 ⁷ |
| Arc Resistance | ASTM D-495 | D48/50 | >180 | >180 | >180 |
| Tensile Modulus (kpsi) | ASTM D-638 | A, 23°C | 267, 202 | 485, 346 | 706, 517 |
| Tensile Strength (kpsi) | ASTM D-882 | A, 23°C | 8.1, 7.5 | 14.9, 11.2 | 19.0, 15.0 |
| Compressive Modulus (kpsi) | ASTM D-695 | A, 23°C | 237 | 327 | 359 |
| Flexural Modulus (kpsi) | ASTM D-790 | A, 23°C | 357 | 437 | 537 |
| Dielectric Breakdown (kV) | ASTM D-149 | D48/50 | >45 | >45 | > 45 |
| Density (g/cm³) | ASTM D-792 Method A | A, 23°C | 2.23 | 2.26 | 2.31 |
| Water Absorption (%) | MIL-S-13949H 3.7.7 IPC TM-650 2.6.2.2 | E1/105 + D24/23 | 0.02 | 0.02 | 0.03 |
| Coefficient of Thermal Expansion (ppm/°C) X Axis Y Axis Z Axis | IPC TM-650 2.4.24 Mettler 3000 Thermomechanical Analyzer | 0°C to 100°C | 25 34 252 | 17 29 217 | 14 21 173 |
| Thermal Conductivity (W/mK) | ASTM E-1225 | 100°C | 0.261 | 0.257 | 0.254 |
| Outgassing Total Mass Loss (%) Collected Volatile Condensable Material (%) Water Vapor Regain (%) Visible Condensate (±) | NASA SP-R-0022A Maximum 1.00% Maximum 0.10% | 125°C, ≤ 10 ⁻⁶ torr | 0.01 0.01 0.01 NO | 0.02 0.00 0.01 NO | 0.02 0.00 0.01 NO |
| Flammability UL File E 80166 | UL 94 Vertical Burn IPC TM-650 2.3.10 | C48/23/50, E24/125 | Meets requirements of UL94-V0 | Meets requirements of UL94-V0 | Meets requirements of UL94-V0 |

¹ Based on a Dielectric Constant of ≤ 2.50, Thickness ≥ 0.020"

<u>Material Availability:</u>

DiClad laminates are supplied with 1/2, 1 or 2 ounce electrodeposited copper on both sides. Other copper weights and rolled copper foil are available. DiClad is available bonded to a heavy metal ground plane. Aluminum, brass or copper plates also provide an integral heat sink and mechanical support to the substrate.

When ordering DiClad products please specify dielectric constant, thickness, cladding, panel size and any other special considerations. Available master sheet sizes include 36" x 48" and 48" x 54".

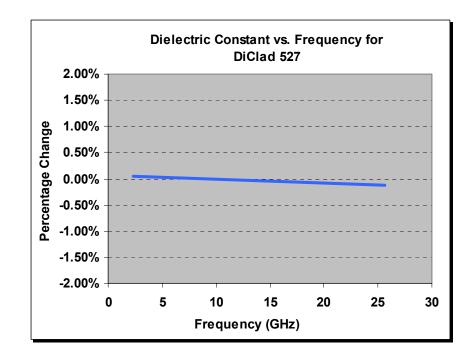


Figure 1

Demonstrates the Stability of Dielectric Constant across Frequency. This information was correlated from data generated by using a free space and circular resonator cavity. This characteristic demonstrates the inherent robustness of the laminates across Frequency, thus simplifying the final design process when working across EM spectrum. The stability of the Dielectric Constant of DiClad over frequency ensures easy design transition and scalability of design.

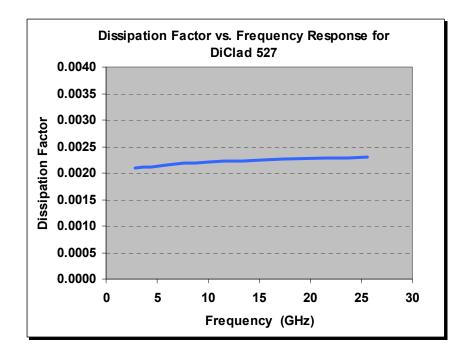


Figure 2

Demonstrates the Stability of Dissipation Factor across Frequency. This characteristic demonstrates the inherent robustness of the Laminates across Frequency, providing a stable platform for high frequency applications where signal integrity is critical to the overall performance of the application.

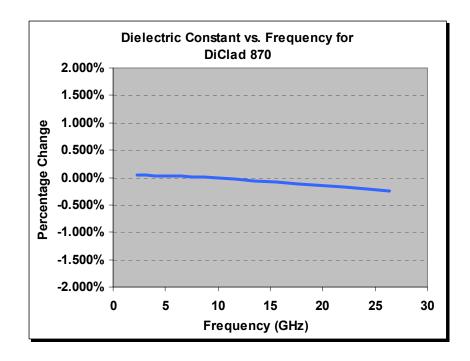


Figure 3

Demonstrates the Stability of Dielectric Constant across Frequency. This information was correlated from data generated by using a free space and circular resonator cavity. This characteristic demonstrates the inherent robustness of the Laminates across Frequency, thus simplifying the final design process when working across EM spectrum. The stability of the Dielectric Constant of DiClad over frequency ensures easy design transition and scalability of design.

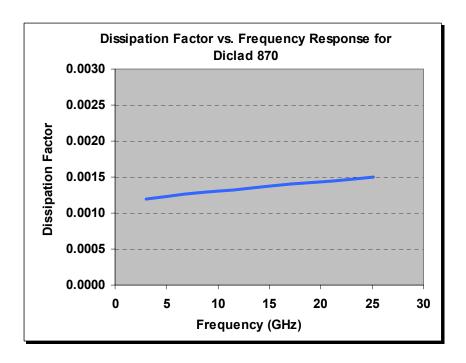


Figure 4

Demonstrates the Stability of Dissipation across Frequency. This characteristic demonstrates the inherent robustness of the laminates across Frequency, providing a stable platform for high frequency applications where signal integrity is critical to the overall performance of the application.

DiClad Series 880

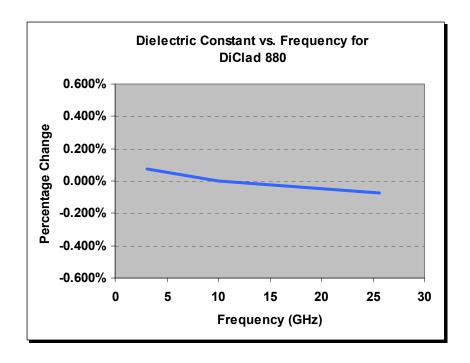


Figure 5

Demonstrates the Stability of Dielectric Constant across Frequency. This information was correlated from data generated by using a free space and circular resonator cavity. This characteristic demonstrates the inherent robustness of the laminates across Frequency, thus simplifying the final design process when working across EM spectrum. The stability of the Dielectric Constant of DiClad over frequency ensures easy design transition and scalability of design.

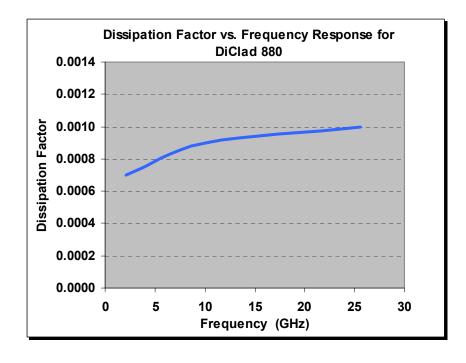


Figure 6

Demonstrates the Stability of Dissipation across Frequency. This characteristic demonstrates the inherent robustness of the laminates across Frequency, providing a stable platform for high frequency applications where signal integrity is critical to the overall performance of the application.